



# 2110MHz-2170MHz, 120W, 28V High Power RF LDMOS FETs

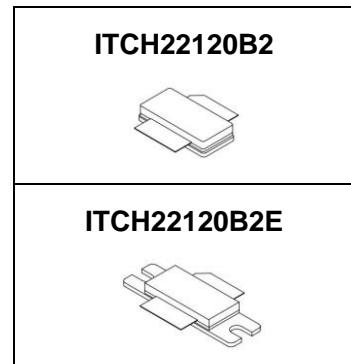
## Description

The ITCH22120B2 is a 120-watt, internally matched LDMOS FET, designed for multicarrier WCDMA/PCS/DCS/LTE base station and ISM applications with frequencies from 2000 to 2200 MHz. It can be used in Class AB/B and Class C for all typical cellular base station modulation formats.

- Typical Performance (On Innogration fixture with device soldered):

VDD = 28 Volts,  $I_{DQ} = 780$  mA, Pulse CW, Pulse Width=10 us, Duty cycle=12% .

Frequency	Gp (dB)	$P_{-1dB}$ (dBm)	$\eta_D@P_{-1}$ (%)	$P_{-3dB}$ (dBm)	$\eta_D@P_{-3}$ (%)
2110 MHz	18.9	50.8	53.8	51.8	56.9
2140 MHz	18.8	50.5	52.4	51.6	56.3
2170 MHz	18.5	50.3	50.7	51.5	54.3



## Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Internally Matched for Ease of Use
- Excellent thermal stability, low HCl drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain--Source Voltage	$V_{DSS}$	70	Vdc
Gate--Source Voltage	$V_{GS}$	-10 to +10	Vdc
Operating Voltage	$V_{DD}$	+32	Vdc
Storage Temperature Range	$T_{STG}$	-65 to +150	°C
Case Operating Temperature	$T_c$	+150	°C
Operating Junction Temperature	$T_j$	+225	°C

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case $T_c = 85^\circ\text{C}$ , $T_j = 200^\circ\text{C}$ , DC test	$R_{\theta JC}$	0.45	°C/W

**Table 3. ESD Protection Characteristics**

Test Methodology	Class
Human Body Model (per JESD22-A114)	Class 2

**Table 4. Electrical Characteristics** (TA = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>DC Characteristics</b>					
Drain-Source Breakdown Voltage ( $V_{GS}=0\text{V}$ ; $I_D=1\text{mA}$ )	$V_{DSS}$	65	70		V



Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 28$ V, $V_{GS} = 0$ V)	$I_{DSS}$			10	$\mu A$
Gate-Source Leakage Current ( $V_{GS} = 10$ V, $V_{DS} = 0$ V)	$I_{GSS}$			1	$\mu A$
Gate Threshold Voltage ( $V_{DS} = 28$ V, $I_D = 600$ uA)	$V_{GS(th)}$		1.8		V
Gate Quiescent Voltage ( $V_{DD} = 28$ V, $I_{DQ} = 800$ mA, Measured in Functional Test)	$V_{GS(Q)}$	2.2	2.7	3.2	V

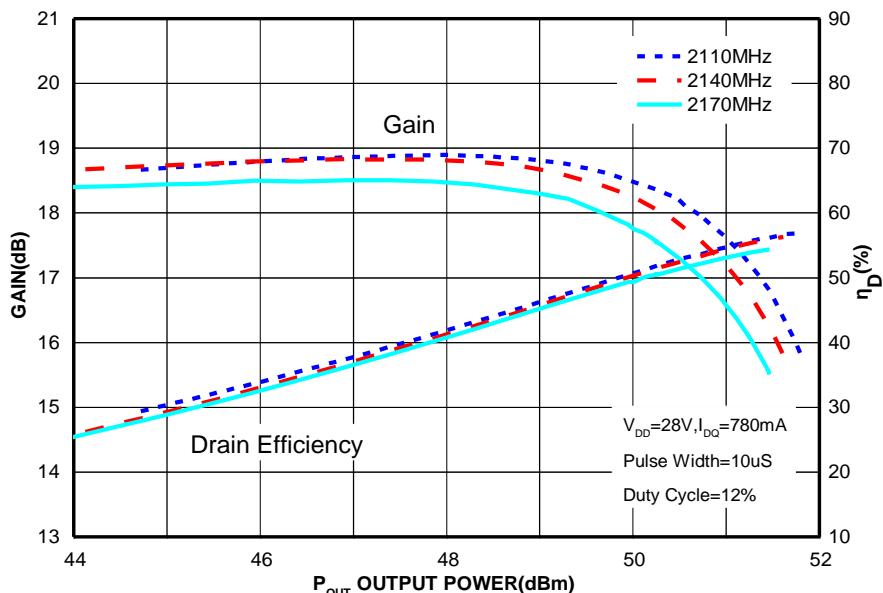
**Functional Tests (In Innogration demo, 50 ohm system)** :  $V_{DD} = 28$  Vdc,  $I_{DQ} = 780$  mA,  $f = 2110$  MHz, Pulse CW, Pulse Width=10 us, Duty cycle=12% .

Power Gain	$G_p$	---	18.9	---	dB
1 dB Compression Point	$P_{-1dB}$	---	50.8	---	dBm
3dB Compression Point	$P_{-3dB}$	---	51.8	---	dBm
Drain Efficiency@P3dB	$\eta_{ID}$	---	56.9	---	%
Input Return Loss	IRL	---	-7	---	dB

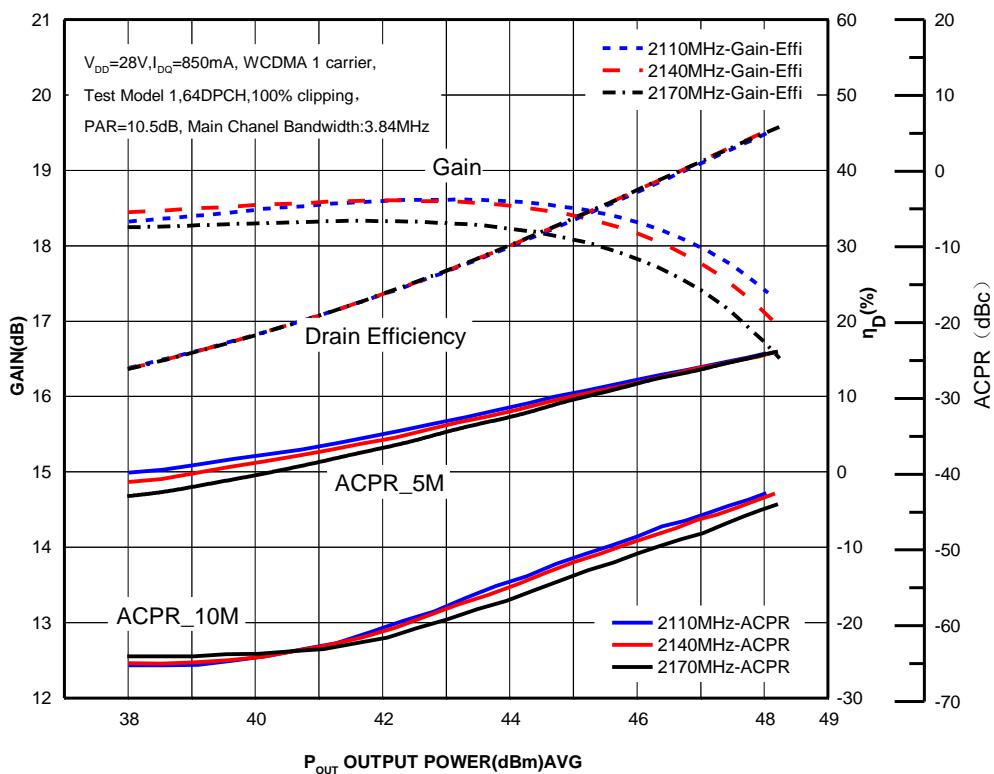
**Load Mismatch (In Innogration Test Fixture, 50 ohm system):**  $V_{DD} = 28$  Vdc,  $I_{DQ} = 800$  mA,  $f = 2110$  MHz

VSWR 10:1 at 120W pulse CW Output Power	No Device Degradation
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## TYPICAL CHARACTERISTICS



**Figure 1. Power gain and drain efficiency as function of  
Pulse output power**

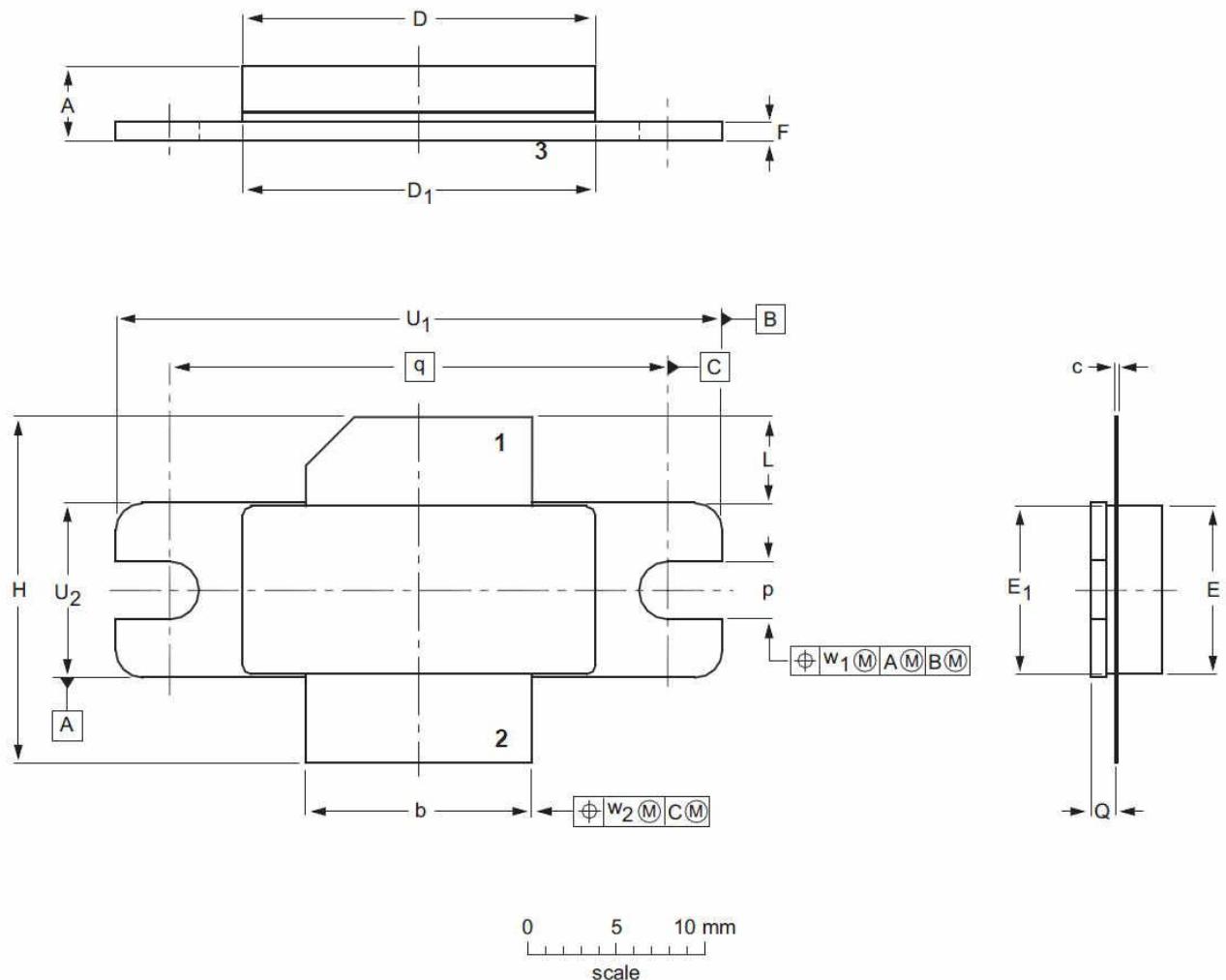


**Figure 2. Single-Carrier WCDMA Power gain and drain efficiency and  
ACPR at 5 MHz and at 10 MHz as function of average output power**



## Package Outline

Flanged ceramic package; 2 mounting holes; 2 leads (1—DRAIN, 2—GATE, 3—SOURCE)

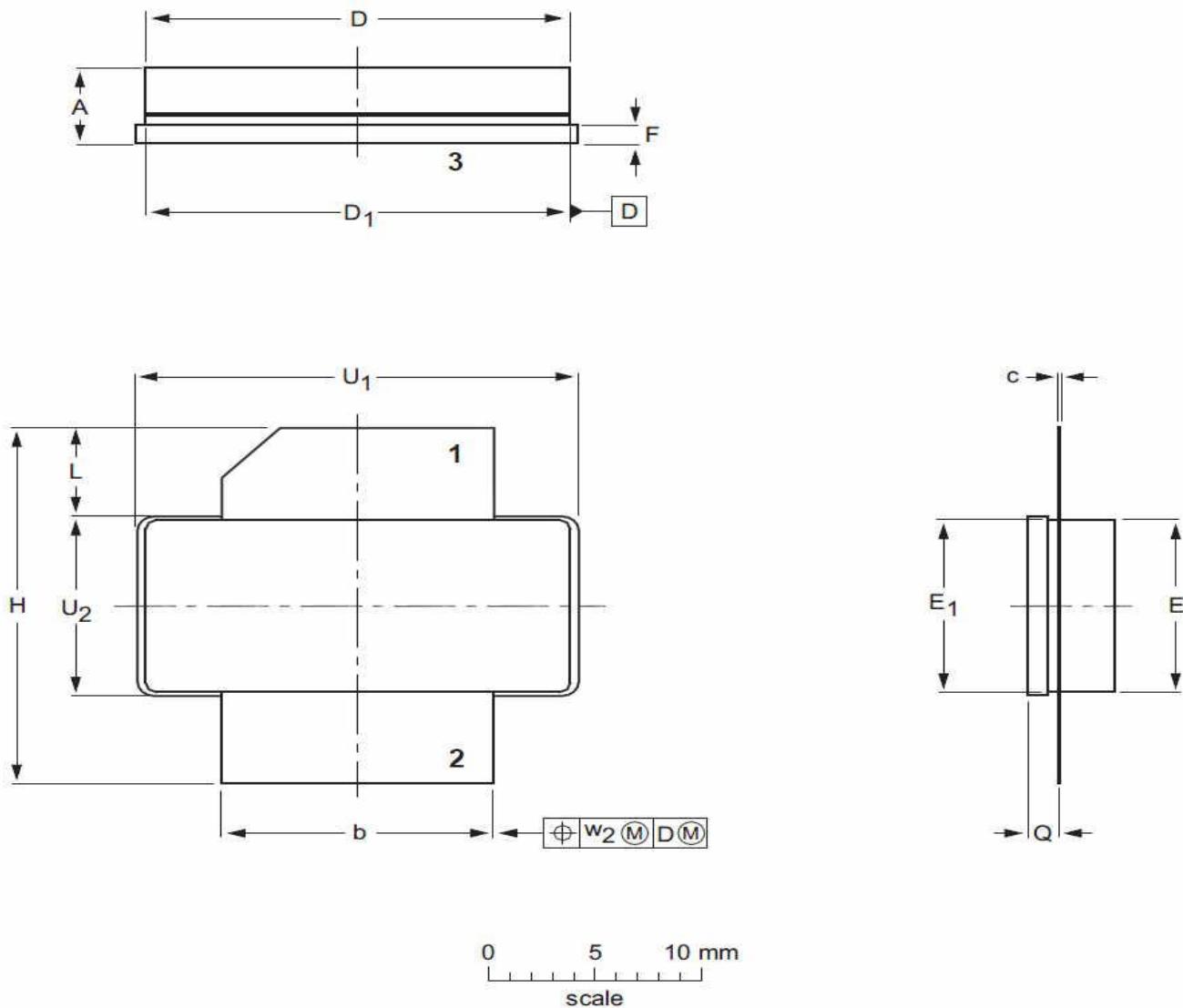


UNIT	<b>A</b>	<b>b</b>	<b>c</b>	<b>D</b>	<b>D<sub>1</sub></b>	<b>E</b>	<b>E<sub>1</sub></b>	<b>F</b>	<b>H</b>	<b>L</b>	<b>p</b>	<b>Q</b>	<b>q</b>	<b>U<sub>1</sub></b>	<b>U<sub>2</sub></b>	<b>W<sub>1</sub></b>	<b>W<sub>2</sub></b>
mm	4.72	12.83	0.15	20.02	19.96	9.50	9.53	1.14	19.94	5.33	3.38	1.70	27.94	34.16	9.91	0.25	0.51
	3.43	12.57	0.08	19.61	19.66	9.30	9.25	0.89	18.92	4.32	3.12	1.45		33.91	9.65		
inches	0.186	0.505	0.006	0.788	0.786	0.374	0.375	0.045	0.785	0.210	0.133	0.067	1.100	1.345	0.390	0.01	0.02
	0.135	0.495	0.003	0.772	0.774	0.366	0.364	0.035	0.745	0.170	0.123	0.057		1.335	0.380		

OUTLINE VERSION	REFERENCE			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
PKG-B2E					03/12/2013



## Earless flanged ceramic package; 2 leads (1—DRAIN、2—GATE、3—SOURCE)



UNIT	A	b	c	D	$D_1$	E	$E_1$	F	H	L	Q	$U_1$	$U_2$	$w_2$
mm	4.72	12.83	0.15	20.02	19.96	9.50	9.53	1.14	19.94	5.33	1.70	20.70	9.91	0.25
	3.43	12.57	0.08	19.61	19.66	9.30	9.25	0.89	18.92	4.32	1.45	20.45	9.65	

OUTLINE VERSION	REFERENCE			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
PKG-B2					03/12/2013



## Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2017/03/27	Rev 1.0	Preliminary Datasheet

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